



Final Program

Future Directions in IC and Package Design Workshop (FDIP)

October 28, 2007, Atlanta, GA

sponsored by:



COMPONENTS, PACKAGING,
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TECHNOLOGY SOCIETY

IEEE



organized by:

CPMT Technical Committee on Electrical Design, Modeling, and Simulation (TC-EDMS)

- 1:15pm - 1:30 pm **Welcome Remarks, Alina Deutsch, IBM, Madhavan Swaminathan, GIT**
- SESSION I: SYSTEM DESIGN**
1:30pm – 4:00 pm
Session Chair: George Katopis – IBM Corporation
- 1:30pm – 2:05pm Signal Bandwidth for High Performance Computing – Dale Becker, IBM Corporation
- 2:05pm – 2:40pm Wireless Proximity Communications for 3D System Integration - Tadahiro Kuroda, Keio University
- 2:40pm – 3:15pm A Critical Assessment of the State of the Art in Multiscale Multiphysics Modeling of Microelectronics - Jayathi Murthy, Purdue University
- 3:15 – 4:00 pm - Refreshment Break**
- SESSION II: POWER DISTRIBUTION**
4:00pm – 5:55 pm
Session Chair: Gregory Taylor, Intel Corporation
- 4:00pm – 4:35pm Power Delivery Challenges for Mobile Platforms – Tawfik Arabi, Intel Corporation
- 4:35pm – 5:10pm Modeling Challenges for Power Distribution Analysis – Madhavan Swaminathan, Georgia Institute of Technology
- 5:10pm – 5:45pm Power Delivery System Design Challenges and Explorations on How to Overcome Them - Jiayuan Fang, Sigrity, Inc.
- 5:45pm – 5:55 pm Closing Remarks, Madhavan Swaminathan, GIT, Alina Deutsch, IBM**
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Presentations will be posted on the IEEE CPMT Society web page at:
<http://www.ewh.ieee.org/soc/cpmt/tc12/>